

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of the claims in the application:

**Listing of Claims:**

Claim 1 (Currently amended) An electronic connector terminal comprising a terminal base material formed by punching a metal thin plate and an Au plating layer covering said terminal base material, said terminal base material further comprising a lateral part having at least one contact and defined as a cut surface of said thin plate through said punching and a planer part defined by front and back faces of a punched-out piece from said thin plate, wherein a thickness of an Au plating layer covering said planer part is thinner than a thickness of an Au plating layer covering said lateral part having said at least one contact.

Claim 2 (Original) The electronic connector terminal of claim 1, wherein a ratio of said thickness of said Au plating layer covering said lateral part and said thickness of said Au plating layer covering said planer part is to be from about 10:1 to 5:1.

Claim 3 (Original) The electronic connector terminal of claim 1, wherein said electronic connector terminal comprises a liner plating layer formed between said terminal base material and said

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• Au plating layer so as to cover said terminal base material.

• Claim 4 (Original) The electronic connector terminal of claim 3, wherein a thickness of a liner plating layer covering said planer part is thinner than a thickness of a liner plating layer covering said lateral part having said at least one contact.

• Claim 5 (Original) The electronic connector terminal of claim 3, wherein a ratio of said thickness of said liner plating layer covering said lateral part and said thickness of said liner plating layer covering said planer part is to be from about 10:1 to 5:1.